

LISTING OF CLAIMS:

1. (Previously presented) A semiconductor device comprising:

a semiconductor chip, which produces heat when operated;

a heat conducting plate for conducting heat provided on one side of the semiconductor chip;

an insulating sheet, which is compressively deformable, also provided on the one side of the semiconductor chip; and

a resin molding covering the semiconductor chip, the plate, and the sheet such that the sheet is exposed from the resin molding.

2. (Previously presented) The semiconductor device of claim 1, wherein the heat conductivity of the insulating sheet is greater than that of the resin molding.

3. (Previously presented) The semiconductor device of claim 2, wherein the insulating sheet is made of silicone rubber.

4-6 (Canceled)

7. (Currently Amended) The semiconductor device of claim 1, wherein the insulating sheet is adhered to the heat conducting plate using a coating resin applied to the heat conducting plate.

8. (Original) The semiconductor device of claim 7, wherein the coating resin is polyamide resin.
9. (Previously presented) The semiconductor device of claim 1, wherein the semiconductor chip forms part of a stack, and the stack includes the plate, and opposite sides of the semiconductor chip are soldered to members of the stack.

10-16. (Canceled)